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1 SSOP16 Package

The standard package of the ZSC31050 is a SSOP16 (5.3mm body width) with lead-pitch 0.65mm. Refer to the *ZSC31050 Data Sheet* for pin assignments.

Weight: ≤ 0.3 g

Package Body Material: Low-stress epoxy

Lead Material: FeNi-Alloy or Cu-Alloy

Lead Finish: solder plating

Lead Form: Z-bends

Figure 1.1 Package View

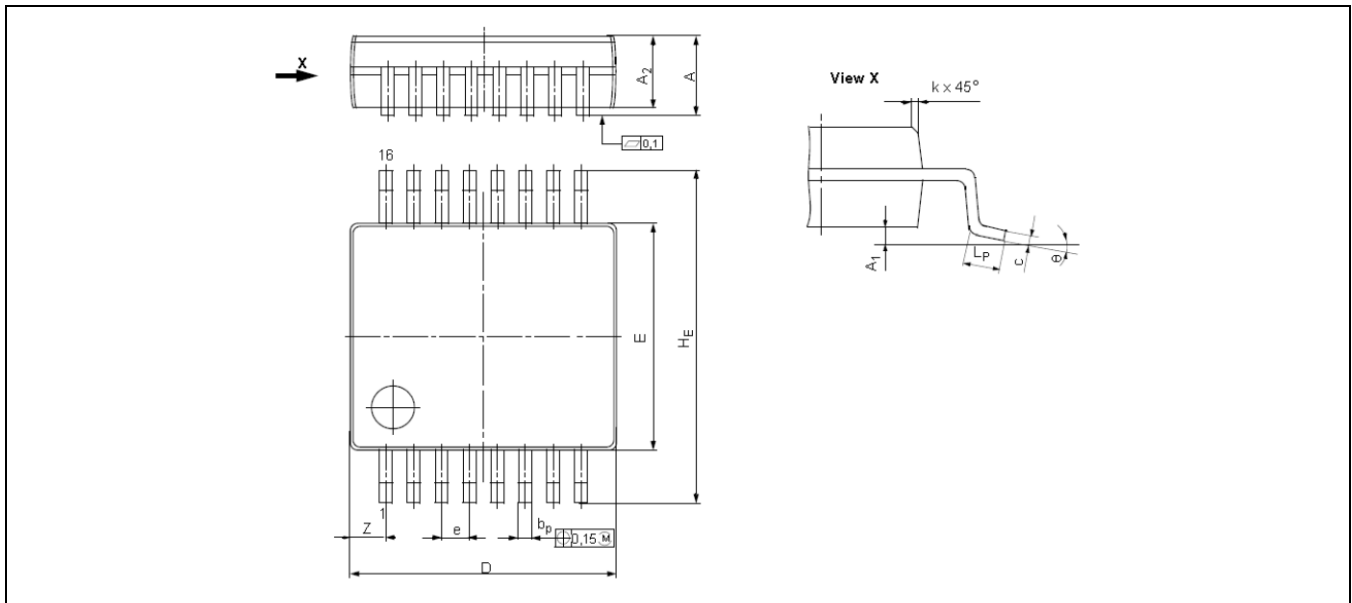


Table 1.1 Package Dimension

Package Dimensions					
Dimension	Value	Dimension	Value	Dimension	Value
A _{max}	1.99	C _{min}	0.09	H _{Emin}	7.65
A _{min}	1.73	C _{max}	0.20	H _{Emax}	7.90
A1 _{min}	0.05	D _{min} *	6.07	k _{min}	0.25
A1 _{max}	0.21	D _{max} *	6.33	LP _{min}	0.63
A2 _{min}	1.68	E _{min} *	5.20	Z _{max}	0.89
A2 _{max}	1.78	E _{max} *	5.38	θ _{min}	0°
b _{Pmin}	0.25	e _{nom}	0.65	θ _{max}	10°
b _{Pmax}	0.38	* without mold-flash			

Table 1.2 Package Marking

Top Side		Comments
1 st Line	ZMDI	
2 nd Line	31050%\$G1	% = Revision Identifier; \$ = Temperature Range Identifier; examples: ZSC31050FEG1, ZSC31050FAG1; ZSC31050FIG1
3 rd Line	YYWW	Package Assembly Date: YEAR,YEAR,WEEK,WEEK

2 Temperature Profile

Refer to calculation sheet *ZMDI Temperature Profile Calculation Sheet* for details.

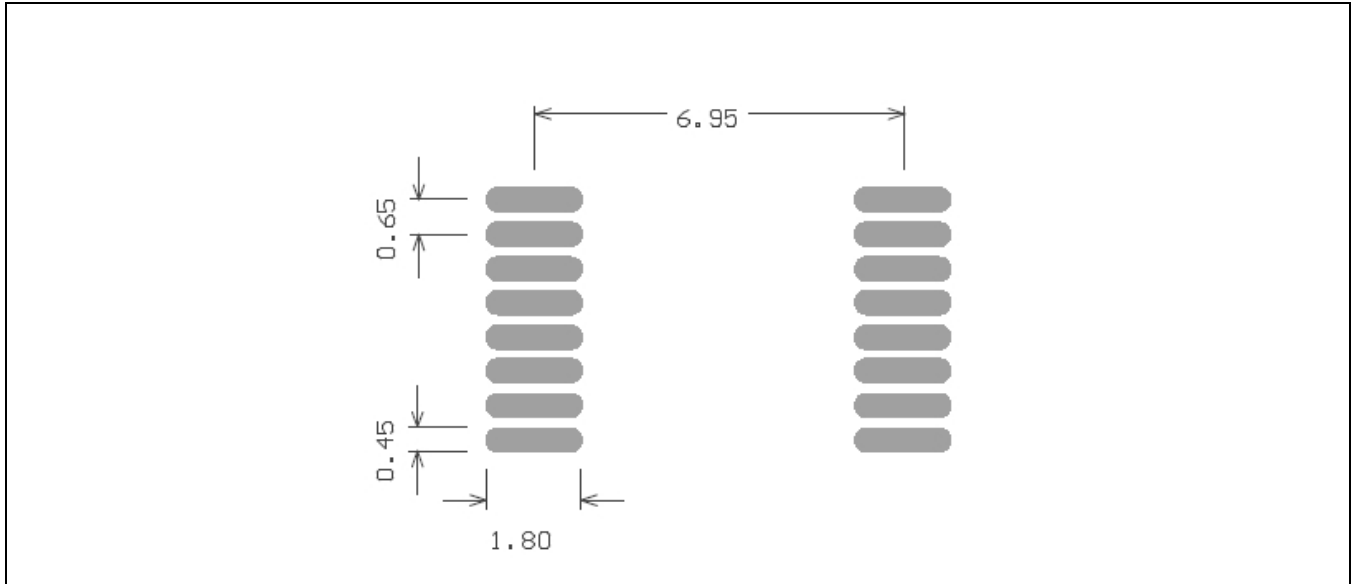
3 Storage Conditions

Table 3.1 Storage Conditions

Parameter	Min	Typ	Max	Unit	Conditions
t _{Storage} , Dry Pack			36	months	Outside of the dry pack: ≤ 40°C temperature and ≤ 90% relatively humidity
t _{Storage} , Tape/Reel (Without Dry Pack)			24	months	-10°C to 50°C and storage at a relative humidity with no condensation Important: Drying before assembly is required.
t _{Storage} , Tape/Reel (Without Dry Pack)			168	hours	≤ 30°C temperature and ≤ 60% relatively humidity

4 Recommended Printed Circuit Board (PCB) Footprint

Figure 4.1 Recommended PCB Footprint



5 Related Documents

Document
ZSC31050 Feature Sheet
ZSC31050 Data Sheet
IDT Temperature Profile Calculation Sheet
ZSC31050 Technical Note – Die Dimensions and Pad Locations *

Visit the ZSC31050 product page (www.IDT.com/ZSC31050) or contact your nearest sales office for the latest version of these documents.

* Documents marked with an asterisk (*) are available on request only.

6 Glossary

Term	Description
SSC	Sensor Signal Conditioner
SSOP	Shrink Small Outline Package

7 Document Revision History

Revision	Date	Description
1.00	May 16, 2013	First release of document as combined die and package information technical note.
1.10	October 15, 2015	Separation of document into separate technical notes for die dimensions and for SSOP16 dimensions. Update for contact information and imagery for cover and headings.
	April 26, 2016	Changed to IDT branding.

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